



PATENT  
Attorney Docket No. 98124x205487

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Wang et al.

Group Art Unit: 1765

Application No. 09/636,161

Examiner: L. Umez-Eronini

Filed: August 10, 2000

For: POLISHING SYSTEM AND  
METHOD OF ITS USE

PRELIMINARY AMENDMENT

Commissioner for Patents  
Washington, D.C. 20231

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MAR 20 2002  
TC 1700

Dear Sir:

Prior to the examination of the above-identified patent application, please enter the following amendments and consider the following remarks.

AMENDMENTS

IN THE SPECIFICATION:

*Replace the paragraph beginning at page 1, line 13, with:*

Integrated circuits are made up of millions of active devices formed in or on a substrate, such as a silicon wafer. The active devices are chemically and physically connected into a substrate and are interconnected through the use of multilevel interconnects to form functional circuits. Typical multilevel interconnects comprise a first metal layer, an interlevel dielectric layer, and sometimes a third and subsequent metal layer. Interlevel dielectrics, such as doped and undoped silicon dioxide ( $\text{SiO}_2$ ) and/or low-k dielectrics, are used to electrically isolate the different metal layers.

*Replace the paragraph beginning at page 5, line 11, with:*

The polishing additive can be any suitable phosphorous-containing compound. Suitable phosphorous-containing compounds include, for example, phosphates (e.g., pyrophosphates, tri-phosphates, condensed phosphates), phosphonic acids (e.g., mono-hosphonic acids, di-phosphonic acids, tri-phosphonic acids, poly-phosphonic acids), and salts of phosphonic acids. Preferred phosphorous-containing compounds include, for